

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4037650

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	ELEMENT SIX TECHNOLOGIES US CORPORATION	09/02/2016
RECEIVING PARTY DATA		
Name:	RFHIC CORPORATION	
Street Address:	RFHIC BLDG. 41-14, BURIM-RO 170 BEON-GIL,	
Internal Address:	DONGAN-GU, ANYANG-SI, GYEONGGI-DO	
City:	ANYANG-SI	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	14055	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14409867
CORRESPONDENCE DATA		
Fax Number:	(408)716-4985	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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NAME OF SUBMITTER:	CHUNG SIK PARK	
SIGNATURE:	/Chung.Park/	
DATE SIGNED:	09/03/2016	
Total Attachments: 4		
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CONFIRMATORY ASSIGNMENT

PARTIES:

- (1) **ELEMENT SIX TECHNOLOGIES US CORPORATION**, of 3901 Burton Drive, Santa Clara, CA95054, United States of America (the "ASSIGNOR") and
- (2) **RFHC CORPORATION**, a Republic of Korea company headquartered in Anyang-Si, Republic of Korea, with offices in Morrisville, North Carolina, United States of America, (the "ASSIGNEE");

each a "PARTY" and together the "PARTIES".

1. DEFINITIONS:

For the purposes of this Assignment:

- 1.1 "PATENTS" shall mean, collectively and severally, the patents and patent applications listed in the SCHEDULE to this Assignment.
- 1.2 "INVENTIONS" shall mean the inventions to which the PATENTS relate.

2. WHEREAS:

- 2.1 By virtue of an agreement between the PARTIES dated 15th July 2016, (the "AGREEMENT") the ASSIGNOR has assigned to the ASSIGNEE all its right title and interest in and to the INVENTION and the PATENTS.
- 2.2 For the avoidance of doubt, and so as to confirm ASSIGNEE's legal title to the same, the Parties have agreed to execute this Assignment for the purpose of ensuring that all ASSIGNOR's rights in the INVENTIONS and PATENTS and all other intellectual property rights relating thereto are vested in ASSIGNEE.

3. IT IS AGREED THAT:

In consideration of the sum of \$1(one United States Dollar) paid by ASSIGNOR to ASSIGNEE, the receipt of which is hereby acknowledged:

- 3.1 ASSIGNOR as necessary hereby confirms the assignment of and assigns to ASSIGNEE, and ASSIGNEE as necessary hereby confirms its acceptance of and accepts all ASSIGNOR's property right title and interest in and to the INVENTIONS and PATENTS for all relevant states including without limitation:
 - (a) the right to apply for and obtain patents in respect of the INVENTIONS in any country in the world;
 - (b) all right, title and interest in and to the PATENTS and all patent applications, patents and supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the same or otherwise relate to the INVENTIONS, including without limitation any divisionals, continuations, continuations-in-part, reissues, re-examination certificates, post-grant reviews, inter partes reviews, supplemental examinations, extensions, renewals and registrations in relation to any thereof and all and any other rights in the inventions comprised in any of the same (hereinafter collectively and severally "the PATENT RIGHTS");
 - (c) the benefit of all priority dates;
 - (d) the right to seek and obtain registrations in any country in the world in respect of any patent deriving from the PATENTS or otherwise included in the PATENT RIGHTS;
 - (e) the right to sue for and obtain injunctive relief, damages and all other relief in respect of any infringement or misuse (whether past present or future) of any of the PATENT RIGHTS or of the rights conferred by publication of any of the same.

- 1.2 Each PARTY authorizes and requests his/her professional representative before any national or regional patent office to insert an appendix signed and dated by the professional representative detailing the filing date and application number of any patent application, patent and/or supplementary protection certificates which may now or at any time in the future derive or result or claim priority from the PATENTS where needed for effective recordal of any such patent application or patent at any national or regional patent office.
- 3.3 ASSIGNOR hereby covenants and agrees to and with ASSIGNEE that, at the time of execution and delivery of the AGREEMENT, ASSIGNOR was the sole and lawful owner of the entire right, title, and interest in and to the INVENTIONS and PATENTS, and that ASSIGNOR had good and full right and lawful authority to sell and convey the same.
- 3.4 ASSIGNOR will, without further consideration, communicate to the ASSIGNEE any facts known to the ASSIGNOR regarding the INVENTION and the PATENTS, sign all lawful papers, execute all oaths, assignments, powers of attorney, applications and any other paper desired by ASSIGNEE to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.4.
- 3.5 At the request and expense of the ASSIGNEE, ASSIGNOR will testify in any legal proceeding to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in any country in the world. ASSIGNOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE under this clause 3.5
- 3.6 ASSIGNOR hereby agrees to execute all such documents and do all such things as may be required by the law of any country in order to record the PATENTS and any other PATENT RIGHTS in the name of ASSIGNEE.
- 3.7 This Assignment shall be governed by the laws of New York, United States of America, and the parties submit to the exclusive jurisdiction of the courts of North Carolina, United States of America in respect of any dispute relating to this Assignment.

Signed on behalf of
ELEMENT SIX TECHNOLOGIES US
CORPORATION

Signature:

Name:

Title:

Date:

Signed on behalf of
RFHIC CORPORATION

Signature:

Name:

Title:

Date:

SCHEDULE

E6 Family Reference	Country	Application Number (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority/provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventor(s)	Original Title	Reference
PF1244	US	11/279553 (12-Apr-2006)	US20060266289 (30-Nov-2006)	US7595507 (29-Sep-2009)		US Provisional Application 60/671411 (13-Apr-2005)	FRANCIS, Daniel; EIECKAM, Felix; WASSERBAUER, John; BABIĆ, Dubravko	Semiconductor Devices having Gallium Nitride Epilayers on Diamond Substrates	PF1244-US-2
	US	12/486098 (12-Apr-2006)	US20100001293 (07-Jan-2010)	US8283672 (09-Oct-2012)	Continuation of US Application 11/279553				PF1244-US-3
	US	12/569486 (12-Jun-2009)	US20100105166 (29-Apr-2010)	US8283189 (09-Oct-2012)	Division of US Application 11/279553				PF1244-US-4
	US	12/608982 (12-Apr-2006)	US2010183798 (16-Jul-2013)	US8945966 (03-Feb-2015)	Division of US Application 12/569486				PF1244-US-5
	US	12/855274 (12-Aug-2010)	Not published prior to issue	US8796843 (05-Aug-2014)		US Provisional Application 61/233390 (12-Aug-2009)	BABIĆ, Dubravko; SCHREIBER, Alex; DHUICK, Quentin	KF and Millimeter-Wave High-Power Semiconductor Device Packaging	PF1246-US-2
PF1246	US	13/407588 (28-Feb-2012)	Not published prior to issue	US8674405 (18-Mar-2014)	Continuation-in-part of US Application 12/486098	US Provisional Application 61/447569 (28-Feb-2011)	BABIĆ, Dubravko; FRANCIS, Daniel; FRANCK, Felix	Gallium-Nitride-on- Diamond Wafers and Devices, and Methods of Manufacture	PF1248-US-2
	US	12/163681 (28-Feb-2012)	US20140141595 (22-May-2014)	US8759134 (24-Jun-2014)	Division of US Application 13/407588				PF1248-US-3
	EP	13/748115 (02-Jun-2013)	EP2870626 (11-May-2015)		National phase of International Application PCT/IB2013/055417 filed 02-Jul-2013, published as WO2014006562 on 09- Jan-2014	US Provisional Application 61/667864 (09-Jul-2012)	DEDUCK, Quentin; FRANCIS, Daniel; LOWE, Frank Yannis; EIECKAM, Felix	Handle for Semiconductor-On- Diamond Wafers and Method of Manufacture	PF1249-EPw-0
PF1249	JP	2015-519469 (02-Jul-2013)	JP2015-522213 (03-Aug-2015)						PF1249-JPw-0
	US	14/409867 (02-Jul-2013)	US20150200254 (16-Jul-2016)						PF1249-USw-0
	EP	13/751987.9 (28-Feb-2013)	EP2820173 (07-Jan-2015)		National phase of International Application PCT/IB2013/078406 filed 28-Feb-2013, published as WO2014130873 on 06- Sep-2013	US Provisional Application 61/604979 (29-Feb-2012)	FRANCIS, Daniel; NASSER-FALLI, Firouz; MATTHEWS, Christopher; LOWE, Frank Yannis; DEDUCK, Quentin; ZAYTSEV, Sergey EIECKAM, Felix	Gallium-Nitride-on- Diamond Wafers, Manufacturing Equipment, and Methods of Manufacture	PF1250-EPw-0
	JP	2014-560054 (28-Feb-2013)	JP2015506479 (30-Mar-2015)						PF1250-JPw-0
	EP	2015-206822 (26-Oct-2015)	JP2016064979 (28-Apr-2016)		Division of JP application 2014-560054				PF1250-JP-2
PF1250	US	13/781054 (28-Feb-2013)	US20130298823 (14-Nov-2013)	US9359693 (07-Jun-2016)					PF1250-US-2

L6 Family Reference	Country	Application Number (Filed-on Date)	Publication Number (Publication Date)	Grant Number (Grant Date)	Parent Application (unless where directly from priority/provisional applications)	Priority/Provisional Application Number (Priority/Provisional Application Date)	Inventor(s)	Official Title	Reference
PF1252	CN	201300055651.4 (24 Apr 2015) 25-Oct-2013	CN104756245 (01-Jul-2015)		National phase of PCT/US2013/066778 filed 25-Oct-2013, published as WO 2014/066740 on 01- May-2014	US Provisional Application 61/719201 (26-Oct-2012)	FRANCIS, Daniel; BABIC, Dabirko; NASSER-FARJI, Firouz; EDELKAM, Felix; EDDICK, Quentin; SMART, Joseph; MATTHEWS, Kristopher; LOWE, Frank Yannis	Method for Manufacturing Electronic Devices with Improved Reliability	PF1252-CNw-0
	EP	13793610.3 (25-Oct-2013) (11-Mar-2015)	EP2912685 (02-Sep-2015)						PF1252-EPw-0
	JP	2015-335829 (25-Oct-2013) (24-Apr-2015)	JP201533774 (26-Nov-2015)						PF1252-JPw-0
	US	14432721 (25-Oct-2013) (31-Mar-2015)	US20130279945 (01-Oct-2015)						PF1252-USw-0
	GB	1415353.0 (29-Aug-2014) (29-Aug-2014)	GB2518752 (01-Apr-2015)			US Provisional Application 61/872803 (02-Sep-2013)	NASSER-FARJI, Firouz	Semiconductor Device Structures Comprising Polycrystalline CVD Diamond with Improved Near-Substrate Thermal Conductivity	PF1264-GB-2
PF1264	EP	14762205.4 (29-Aug-2014) (22-Jun-2016)	EP3042389 (13-Jul-2016)		National phase of PCT/US2014/053541 filed 29-Aug-2014, published as WO 2015/031833 on 05- Mar-2015	GB Priority Application 1319117.6 (30-Oct-2013)			PF1264-EPw-0
	JP	2016-540296 (29-Aug-2014) (02-Mar-2016)							PF1264-JPw-0
	US	14909791 (29-Aug-2014) (03-Feb-2016)	US20160197627 (07-Jul-2016)						PF1264-USw-0